



Title of Change:	Copper thick film elimination from Rhythm hybrid family products.							
Proposed first ship date:	20 January 2017							
Contact information:	Contact your local ON Semiconductor Sales Office or <Brenda.Johnston@onsemi.com>							
Samples:	Contact your local ON Semiconductor Sales Office							
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Tara.McDonald@onsemi.com>.							
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.							
Change Part Identification:	There is no change to the part identification. The part numbers will continue to be the same. Change tracking will be done based on work order number which will be communicated on request.							
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☒ Other <u>Hybrid Assembly</u>							
Change Sub-Category(s): ☐ Manufacturing Site Change/Addition ☐ Manufacturing Process Change ☒ Material Change ☐ Product specific change ☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other: _____								
Sites Affected: ☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : <u>ON Burlington, Canada</u> ☐ External Foundry/Subcon site(s)								
Description and Purpose: This is a Final Notification that announces the replacement of copper thick film with Silver thick film within the under-bump I/O metallization layer. This change is being made to consolidate all BOM design methodologies at the Burlington manufacturing site.								
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 33%;">Material to be changed</th> <th style="width: 33%;">Before Change Description</th> <th style="width: 33%;">After Change Description</th> </tr> </thead> <tbody> <tr> <td>I/O Under-bump Thick Film</td> <td>I/O Copper Thick Film</td> <td>I/O Silver based Thick Film</td> </tr> </tbody> </table>			Material to be changed	Before Change Description	After Change Description	I/O Under-bump Thick Film	I/O Copper Thick Film	I/O Silver based Thick Film
Material to be changed	Before Change Description	After Change Description						
I/O Under-bump Thick Film	I/O Copper Thick Film	I/O Silver based Thick Film						

**Reliability Data Summary:****QV DEVICE NAME : R3910-CFAB-E1****PACKAGE : SIP-25**

Test	Specification	Condition	Interval	Results
HAST	JESD22-A110	130°C, 85% RH, 1.3V	96 hrs	0/75
THB	JESD22-A101	85°C, 85% RH, 1.3V	288 hrs	0/69
PC	J-STD-020 JESD-A113	MSL4 @ 240°C		
SD	JSTD002	Method S1: MSL4 PC soak Reflow Ta = 240C		0/ 10
		Custom Method: MSL4 PC soak Point to Point Ta = 300C		0/10

Electrical Characteristic Summary: Electrical characteristics are not impacted**QV DEVICE NAME :** Rhythm Family**PACKAGE :** Hybrid Ceramic SIP**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
R3910-CFAB-E1B	R3910-CFAB-E1
R3910-CFAB-E1T	
SA3400-E1-T	
SA3400-E1	
R3920-CFAB-E1T	
R3920-CFAB-E1B	
SB3229-E1	
SA3229-E1	
SA3229-E1-T	
SB3231-E1-T	
SB3231-E1	
SB3230-E1-T	
SB3230-E1	
SB3229-E1-T	